ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and Par	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances v s all lower	vithin the manufactu level materials for v	rer listed	item. Note nanufactur	: if the item is an as er has engineering	sembly with low responsibility.	
IPC Web Site for Information on IPC-1752 Standard For				Form Type Distribute						ials and M	ls and Mfg Information			
upplier Information														
Company name* Compa			ompany unique ID			Unique ID Authority				Respon	Response Date*			
nsemi								2023-00	2023-06-08					
ntact Name Title - Contact				Phone - Contact*				Email - Contact*						
Product-Env-Stewards Product Enviro			ro Compliance		NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representati			entative !			Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	lanufacturing Site		Weight*	UOM	Unit Type	
	NCP811	NCP81156MNTBG MOSFET Driver			202			T	TH6		9.1	mg	Each	
Ianufacturing Proccess Informa	tion							İ						
Terminal Plating / Grid Array Ma	aterial	al Terminal Base Alloy J		J-STD-020 MSI	L Rating	Peak Process Body Ten		emperature	ature Max Time at Peak T		ture Nun	nber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperatu	ire during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

sigma range of distribution unless otherwise noted).

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material Weight Unit of M		Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Die Attach	0.07	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.014	mg
			Supplier	Silver (Ag)	7440-22-4		0.056	mg
Lead Frame	3.71	mg	Supplier	Silver (Ag)	7440-22-4		0.0371	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0045	mg
			Supplier	Iron (Fe)	7439-89-6		0.0872	mg
			Supplier	Copper (Cu)	7440-50-8		3.5801	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0011	mg
Mold Compound-Black	5.0	mg		Epoxy resin	proprietary data		0.25	mg
			Supplier	Phenolic Resin	Proprietary Data		0.115	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.25	mg
			Supplier	Carbon Black (C)	1333-86-4		0.02	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.115	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.25	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0195	mg